

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of :  
:   
Sasson R. SOMEKH et al. :   
:   
Serial No. unassigned : Group Art Unit:  
:   
Filed: herewith : Examiner:

For: MULTI-TOOL CONTROL SYSTEM, METHOD AND MEDIUM

**INFORMATION DISCLOSURE STATEMENT**

Honorable Commissioner for Patents  
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

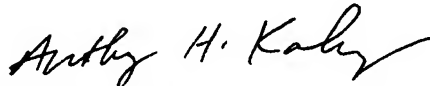
In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of publication indicated for an item is taken from the face of the item, and Applicant reserves the right to prove that the date of publication is in fact different.

The references listed on Sheets 1-19 of Form PTO-1449 were cited by or submitted to the U.S. Patent and Trademark Office in parent application Serial No. 09/469,227, filed December 22, 1999, which is relied upon for an earlier filing date under 35 USC § 120. Copies of these references are not attached under 37 CFR 1.98(d).

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

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Date: Oct 17 2003

<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</b>				ATTY. DOCKET NO. 004393 USA/02/MTCG/PCTRL/JW		SERIAL NO. unassigned	
				APPLICANT Sasson R. SOMEKH			
				FILING DATE herewith		GROUP	
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	3,205,485	09/07/65	Noltingk			10/21/60	
	3,229,198	01/11/66	Libby			09/28/62	
	3,767,900	10/23/73	Chao et al.			06/23/71	
	3,920,965	11/18/75	Sohrwardy			03/04/74	
	4,000,458	12/28/76	Miller et al.			08/21/75	
	4,302,721	11/24/81	Urbanek et al.			05/15/79	
	4,368,510	01/11/83	Anderson			10/20/80	
	4,616,308	10/07/86	Morshedi et al.			12/02/85	
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	5,283,141	02/01/94	Yoon et al.			03/05/92	
	5,295,242	03/15/94	Mashruwala et al.			11/02/90	
	5,309,221	05/03/94	Fischer et al.			12/31/91	
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	5,329,463	07/12/94	Sierk et al.			01/13/93	
	5,338,630	08/16/94	Yoon et al.			11/18/93	
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	5,961,369	10/05/99	Bartels et al.			06/04/98	
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	5,963,881	10/05/99	Kahn et al.			10/20/97	
	5,978,751	11/02/99	Pence et al.			02/25/97	
	5,982,920	11/09/99	Tobin, Jr. et al.			01/08/97	
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	6,036,349	03/14/00	Gombar			07/26/96	
	6,041,270	03/21/00	Steffan et al.			12/05/97	
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	6,064,759	05/16/00	Buckley et al.			11/06/97	
	6,072,313	06/06/00	Li et al.			06/17/97	
	6,078,845	06/20/00	Friedman			11/25/96	
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	6,136,163	10/24/00	Cheung et al.			03/05/99	
	6,141,660	10/31/00	Bach et al.			07/16/98	
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	6,148,099	11/14/00	Lee et al.			07/03/97	
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	6,159,075	12/12/00	Zhang			10/13/99	
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	6,161,054	12/12/00	Rosenthal et al.			09/17/98	
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	6,172,756	01/09/01	Chalmers et al.			12/11/98	
	6,173,240	01/09/01	Sepulveda et al.			11/02/98	
	6,175,777	01/16/01	Kim			01/16/98	
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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	6,183,345	02/06/01	Kamono et al.			03/20/98	
	6,185,324	02/06/01	Ishihara et al.			01/31/95	
	6,191,864	02/20/01	Sandhu			02/29/00	
	6,192,291	02/20/01	Kwon			10/08/98	
	6,197,604	03/06/01	Miller et al.			10/01/98	
	6,204,165	03/20/01	Ghoshal			06/24/99	
	6,210,983	04/03/01	Atchison et al.			06/15/99	
	6,211,094	04/03/01	Jun et al.			08/23/99	
	6,214,734	04/10/01	Bothra et al.			11/20/98	
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	6,278,899	08/21/01	Piche et al.			10/06/98	
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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
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<b>FOREIGN PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	61-66104	04/04/86	Japan			X	
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	06-252236	09/09/94	Japan			X	
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						Yes	No
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